



RoHS Compliance Declaration

Picochip hereby declares that its semiconductor products supplied in component form as “lead-free” or “RoHS compliant” are in compliance with European Union Directive 2002/95/EC (RoHS Directive) of the European Parliament and of the Council of 27th January 2003, amended on 21st October 2005, as of the Effective Date of this document.

This declaration relates specifically to the following products: **PC102 (Flip Chip)**.

Substance	Threshold limit (ppm)
Cadmium (Cd)	< 100
Hexavalent Chromium (Cr ⁶⁺)	< 1000
Mercury (Hg)	< 1000
Polybrominated Biphenyls (PBB)	< 1000
Polybrominated Diphenyl Ethers (PBDE)	< 1000

Note that Flip Chip devices may contain lead, as permitted under Exemption 15 in the Annex to the Directive: *‘Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.’* Lead is not used elsewhere.

Compliant devices are marked in accordance with JEDEC Standard JESD97.

Printed circuit board products are not covered by this declaration.

Effective date of this document: **1-Jan-2006**.

The information is accurate to the best of our knowledge, based on information provided to us by our suppliers.

Signed on behalf of Picochip Designs Limited:

Name: _____ Michael P Davison Date:
Director of Operations

Name: _____ Peter Claydon Date:
Chief Operating Officer